Back End Electronics in LAr Phase-II Upgrade

BROOKHAVEN NATIONAL LABORATORY

Outline

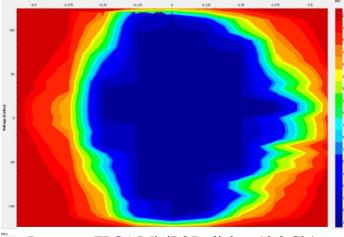
- BNL's Interests
- Proposed BNL's Contribution
- Resources

BNL's Interests

- BNL has been working on the R&D of BE electronics for LAr upgrade since 2005
- Focused on key technologies to enable the breakthrough and optimized system architecture for overall LAr readout and trigger readout electronics systems
 - High speed parallel optical links
 - High performance FPGA with high speed transceivers and high speed DSP
 - Industrial standard platform (ATCA) to house the new BE electronics system
 - Modular design (AMC) to ease the development and make efficient use of expertise from collaboration
 - Close collaboration with US universities (UAZ, SBU) and other international LAr institutes
 - First ATCA module with UAZ in 2008/09
 - Development of AMC module with SBU in 2012/13

BNL's Interests





Processor FPGA/MiniPODs link at 12.8 Gb/s
-3 FPGA with 13.1Gb/s GTH

- FMC MicroPOD Mezzanine
 - Evaluation of both MicroPOD and custom cooling solution
 - First demonstration of non-symmetrical transceiver speeds in FPGA
- Joint BNL/RAL 10Gb/s Link Test in 2013
 - Characterization test of > 10Gbps parallel optical links
 - Enable the > 6.4 Gb/s link speed interface between LAr and L1Calo, currently 11.2 Gb/s
- This has been documented LAr Phase-I Upgrade TDR
 - Important to the ATLAS LAr Phase-I upgrade project and also the US responsibility of BE electronics in USATLAS Phase-I construction project
- Recently gFEX pre-prototype demonstrated 80 links running at 12.8Gbps simultaneously

Proposed BNL's Contribution

- Evaluation and development of key technologies
 - High speed parallel optical links
 - > 25Gbps parallel optical transceivers CFP4, QSFP28, Firefly, Duplex MiniPOD
 - High performance FPGA with high speed transceivers and high speed DSP
 - Xilinx Ultrascale & Ultrascale+ FPGA
 - BNL was responsible of BE high speed data transmission in USATLAS Phase-I construction project in FY14
- Development of LPPR (Liquid Argon Pre-Processor) to interface to LFEB in front end and L1Global/FELIX in TDAQ
 - Focus on board design with FPGA and optical transceivers
 - Recent experience: gFEX & PCIe card for LTDB test
 - Contribute to the firmware development
 - Recent experience: GBT firmware for FELIX, and infrastructure firmware (link & parallel bus) for gFEX

Resources

R&D Phase

 BNL can contribute 0.5 FTE EE per year for BE electronics in USATLAS LAr Phase-II upgrade

Construction Phase

 BNL can contribute 2 FTE EE per year for BE electronics in USATLAS LAr Phase-II construction project

Proposed Tasks

- Lead the design and integration of LPPR, with focus on the high speed parallel optical links and high performance FPGA
- Contribute to the firmware development of LPPR
- Work closely with university groups
- Involvement will be determined by the overall plan of USATLAS Phase-II upgrade